



### B150AF-B160AF

### **1.0A SCHOTTKY BARRIER RECTIFIER**

### **Product Summary**

### B150AF/B160AF

V <sub>RRM</sub> (V)	I <sub>0</sub> (A)	V <sub>F</sub> (MAX) (V) @ +25°C	I <sub>R(MAX)</sub> (mA) @ +25°С
50	1	0.65	0.10
60	1	0.65	0.20

### **Description and Applications**

The Schottky rectifier providing low  $V_F$  and excellent reverse leakage stability at high temperatures, this device is ideal for use in general rectification applications such as:

- Boost Diode
- Blocking Diode
- Recirculating Diode

### **Features and Benefits**

- Reduced Low Forward Voltage Drop (V<sub>F</sub>); Better Efficiency and Cooler Operation
- Reduced High-Temperature Reverse Leakage; Increased Reliability against Thermal Runaway Failure in High Temperature Operation
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Mechanical Data**

- Case: SMAF
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
- Weight: 0.036 grams (Approximate)

SMAF



Top View

### Ordering Information (Note 4)

Part Number	Case	Packaging
B150AF-13	SMAF	10,000/Tape & Reel
B160AF-13	SMAF	10,000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**



B1XXAF = Product Type Marking Code, ex: B150AF JII = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 7 for 2017) WW = Week Code (01 to 53)



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	B150AF	B160AF	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	50	60	V
Average Rectified Output Current	Ι <sub>Ο</sub>		1	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	3	0	А

# Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R <sub>θJA</sub>	95	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R <sub>θJC</sub>	45	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

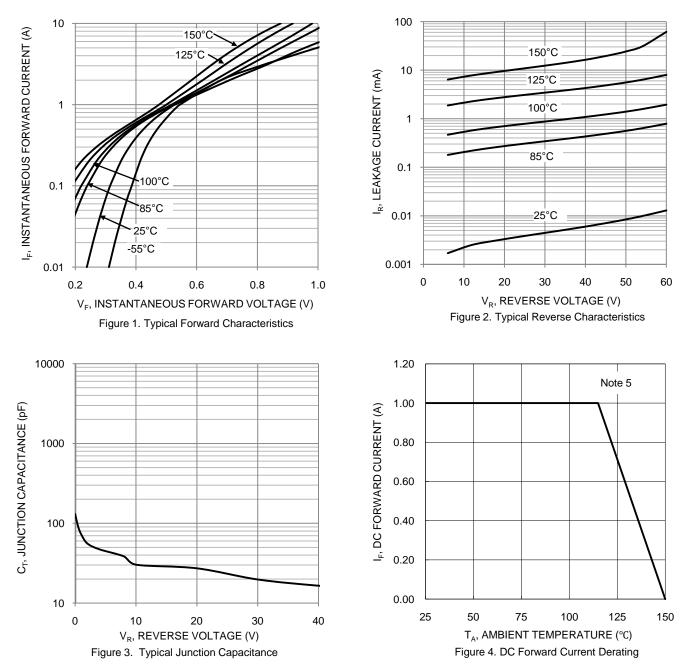
### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop	VF	_	0.53 0.50	0.65		I <sub>F</sub> = 1A, T <sub>J</sub> = +25°C I <sub>F</sub> = 1A, T <sub>J</sub> = +125°C
B150AF Leakage Current (Note 6) B160AF	I <sub>R</sub>		0.015 0.02 7.5	0.10 0.20 —	mA	$V_R = 50V, T_J = +25^{\circ}C$ $V_R = 60V, T_J = +25^{\circ}C$ $V_R = 60V, T_J = +125^{\circ}C$
Typical Capacitance	CT		45	_	pF	$V_R = 4.0V, f = 1MHz$

Notes: 5. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pad. 6. Short duration pulse test used to minimize self-heating effect.



## B150AF-B160AF

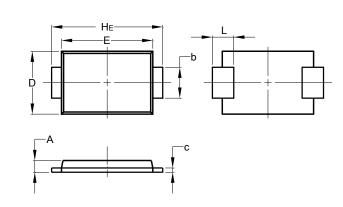


B150AF-B160AF Document number: DS39505 Rev. 2 - 2



## **Package Outline Dimensions**

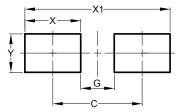
Please see http://www.diodes.com/package-outlines.html for the latest version.



SMAF				
Dim	Min	Max		
Α	0.90	1.10		
b	1.25	1.65		
С	0.10	0.40		
D	2.25	2.95		
E	3.95	4.60		
HE	4.80	5.60		
L	0.50	1.50		
All Dimensions in mm				

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Ý	1.70

SMAF

SMAF

Dimensions	Value (in mm)
С	4.00
G	1.50
Х	2.50
X1	6.50
Y	1.70



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